

REMARKS

Entry of the above amendments to the specification is earnestly solicited. Support for the amendments to the specification includes the description in Table 4 (e.g., sample 32). An early and favorable first action on the merits is earnestly solicited.

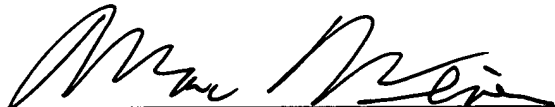
Attached hereto is a marked-up version of the changes made to the application by this Amendment.

If the Examiner has any questions concerning this application, he is requested to contact Applicants' representative, Marc S. Weiner, in the Washington metropolitan area at the telephone number listed below.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17; particularly, extension of time fees.

Respectfully submitted,

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By 

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION

The paragraph beginning on page 14, line 1 and ending on line 9, has been amended as follows:

On the other hand, the alloying elements according to the present invention are not added to Comparative Sample No. 32 shown in Table 3. Namely, oxygen-free copper is melted and cast into an ingot under Ar protective atmosphere. The ingot is worked into a foil, which is then bonded with polyimide. Since the material is pure copper, the electric conductivity is high. However, 180° Peeling strength is 7.0N/cm, hence the bonding strength is unsatisfactory. When such foil is laminated in a printed circuit board, there is a danger of peeling. Since the tensile strength is [less than] as small as 400N/mm², the handling performance is poor.